



2x512Kx8 DUALITHIC™ SRAM

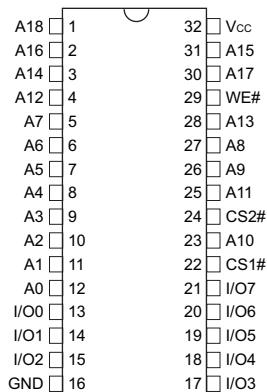
FEATURES

- Access Times 70, 85, 100ns
- Evolutionary, Corner Power/Ground Pinout
- Packaging:
 - 32 pin, Hermetic Ceramic DIP (Package 300)
- Organized as two banks of 512Kx8
- Commercial, Industrial and Military Temperature Ranges
- 5 Volt Power Supply
- Low Power CMOS
- TTL Compatible Inputs and Outputs
- Output Enable Internally tied to GND.

* This product is under development, is not qualified or characterized and is subject to change without notice.

Pin Configuration FOR WS1M8-XCX

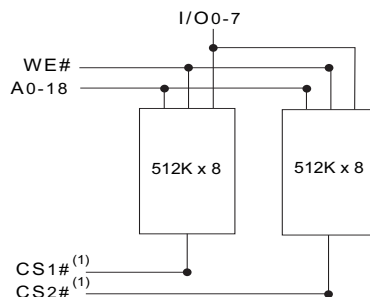
32 DIP Top View



Pin Description

A0-18	Address Inputs
I/O0-7	Data Input/Output
CS1-2#	Chip Selects
WE#	Write Enable
Vcc	+5.0V Power Supply
GND	Ground

Block Diagram



NOTE:

1. CS1# and CS2# are used to select the lower and upper 512Kx8 of the device. CS1# and CS2# must not be enabled at the same time.



ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Min	Max	Unit
Operating Temperature	T _A	-55	+125	°C
Storage Temperature	T _{STG}	-65	+150	°C
Signal Voltage Relative to GND	V _G	-0.5	V _{CC} +0.5	V
Junction Temperature	T _J		150	°C
Supply Voltage	V _{CC}	-0.5	7.0	V

TRUTH TABLE

CS#	WE#	Mode	Data I/O	Power
H	X	Standby	High Z	Standby
L	H	Read	Data Out	Active
L	L	Write	Data In	Active

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Max	Unit
Supply Voltage	V _{CC}	4.5	5.5	V
Input High Voltage	V _{IH}	2.2	V _{CC} + 0.3	V
Input Low Voltage	V _{IL}	-0.3	+0.8	V
Operating Temp. (MIL)	T _A	-55	+125	°C

CAPACITANCE

T_A = +25°C

Parameter	Symbol	Conditions	Max	Unit
Input capacitance	C _{IN}	V _{IN} = 0V, f = 1.0 MHz	28	pF
Output capacitance	C _{OUT}	V _{OUT} = 0V, f = 1.0 MHz	28	pF

This parameter is guaranteed by design but not tested.

DC CHARACTERISTICS

V_{CC} = 5.0V, V_{SS} = 0V, -55°C ≤ T_A ≤ +125°C

Parameter	Sym	Conditions	Min	Max	Units
Input Leakage Current	I _{LI}	V _{CC} = 5.5, V _{IN} = GND to V _{CC}		10	μA
Output Leakage Current	I _{LO} ¹	CS# = V _{IH} , V _{OUT} = GND to V _{CC}		10	μA
Operating Supply Current	I _{CC} ¹	CS# = V _{IL} , f = 5MHz, V _{CC} = 5.5		55	mA
Standby Current	I _{SB} ¹	CS# = V _{IH} , f = 5MHz, V _{CC} = 5.5		2	mA
Output Low Voltage	V _{OL}	I _{OL} = 2.1mA		0.4	V
Output High Voltage	V _{OH}	I _{OH} = -1.0mA	2.4		V

NOTE: DC test conditions: V_{IH} = V_{CC} - 0.3V, V_{IL} = 0.3V

1. OE# is internally tied to GND.

DATA RETENTION CHARACTERISTICS

-55°C ≤ T_A ≤ +125°C

Characteristic	Sym	Conditions	Min	Typ	Max	Units
Data Retention Supply Voltage	V _{DR}	CS# ≥ V _{CC} - 0.2V	2.0		5.5	V
Data Retention Current	I _{CCDR1}	V _{CC} = 3V		150	800*	μA

* Also available in Low Power version. Please call factory for information.



AC CHARACTERISTICS

 $V_{CC} = 5.0V$, $GND = 0V$, $-55^{\circ}C \leq T_A \leq +125^{\circ}C$

Parameter Read Cycle	Symbol	-70		-85		-100		Units
		Min	Max	Min	Max	Min	Max	
Read Cycle Time	t_{RC}	70		85		100		ns
Address Access Time	t_{AA}		70		85		100	ns
Output Hold from Address Change	t_{OH}	0		0		0		ns
Chip Select Access Time	t_{ACS}		70		85		100	ns
Chip Select to Output in Low Z	t_{CLZ}^1	5		5		5		ns
Chip Disable to Output in High Z	t_{CHZ}^1		25		25		25	ns

1. This parameter is guaranteed by design but not tested.

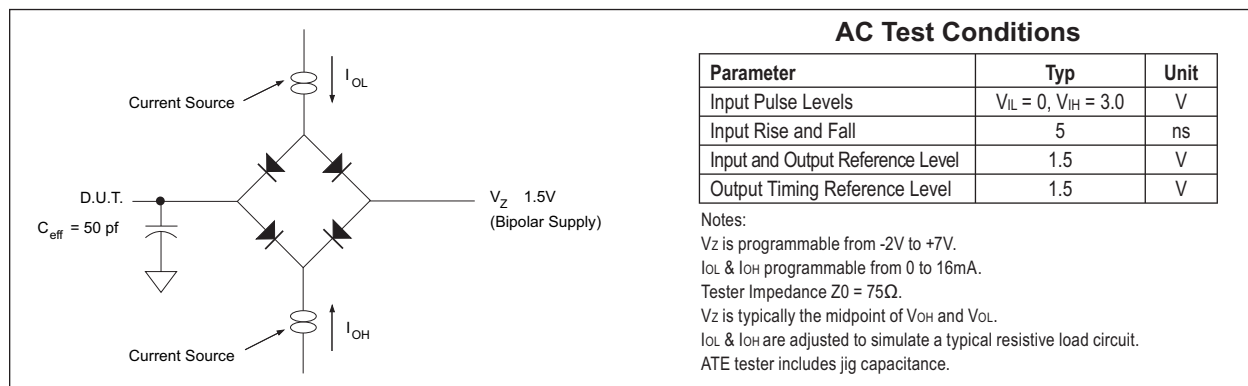
AC CHARACTERISTICS

 $V_{CC} = 5.0V$, $GND = 0V$, $-55^{\circ}C \leq T_A \leq +125^{\circ}C$

Parameter Write Cycle	Symbol	-70		-85		-100		Units
		Min	Max	Min	Max	Min	Max	
Write Cycle Time	t_{WC}	70		85		100		ns
Chip Select to End of Write	t_{CW}	60		75		80		ns
Address Valid to End of Write	t_{AW}	60		75		80		ns
Data Valid to End of Write	t_{DW}	30		30		40		ns
Write Pulse Width	t_{WP}	50		50		60		ns
Address Setup Time	t_{AS}	0		0		0		ns
Address Hold Time	t_{AH}	5		5		5		ns
Output Active from End of Write	t_{OW}^1	5		5		5		ns
Write Enable to Output in High Z	t_{WHZ}^1		25		25		35	ns
Data Hold Time	t_{DH}	0		0		0		ns

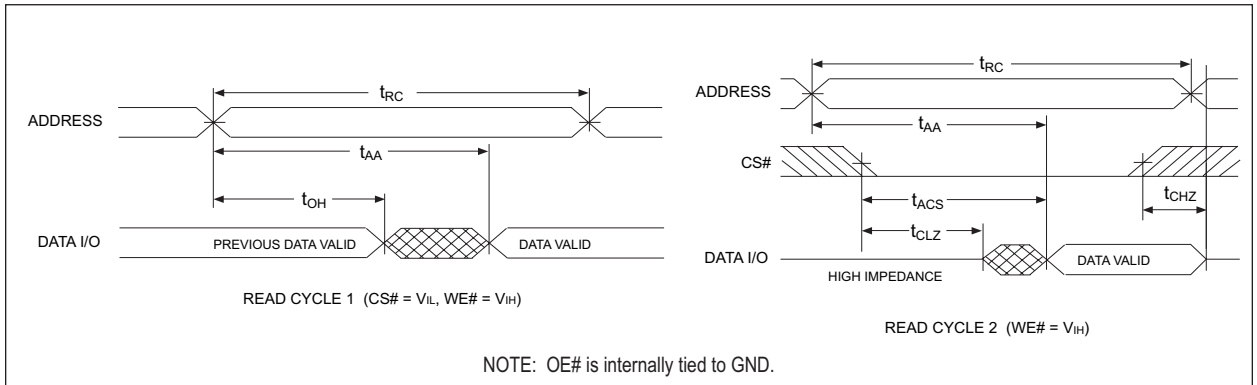
1. This parameter is guaranteed by design but not tested.

AC TEST CIRCUIT

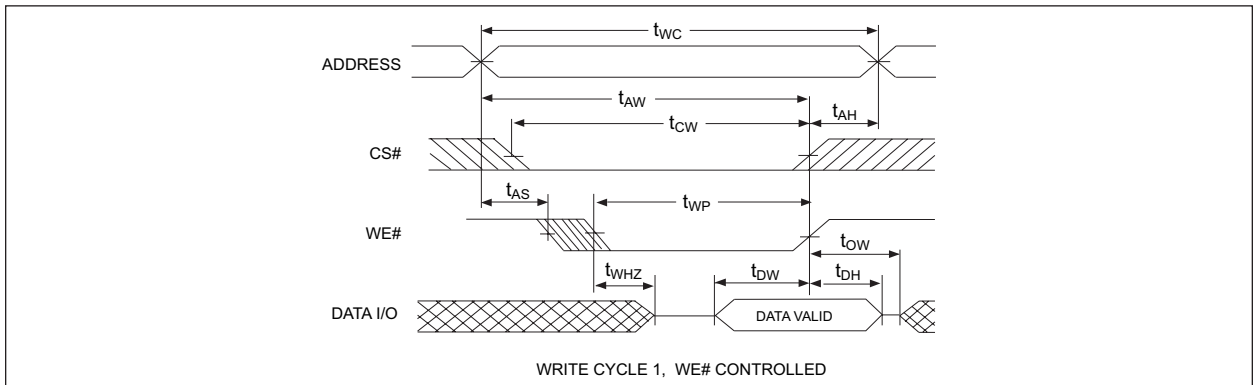




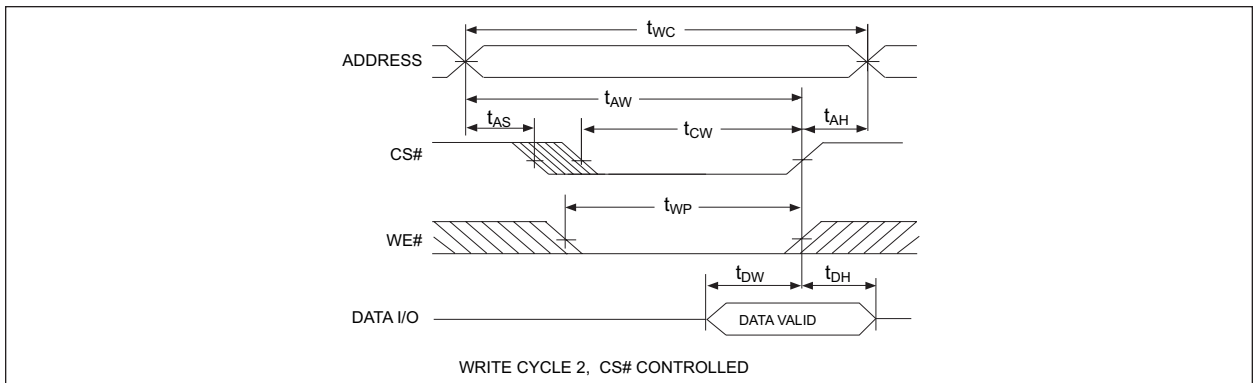
TIMING WAVEFORM – READ CYCLE



WRITE CYCLE – WE# CONTROLLED

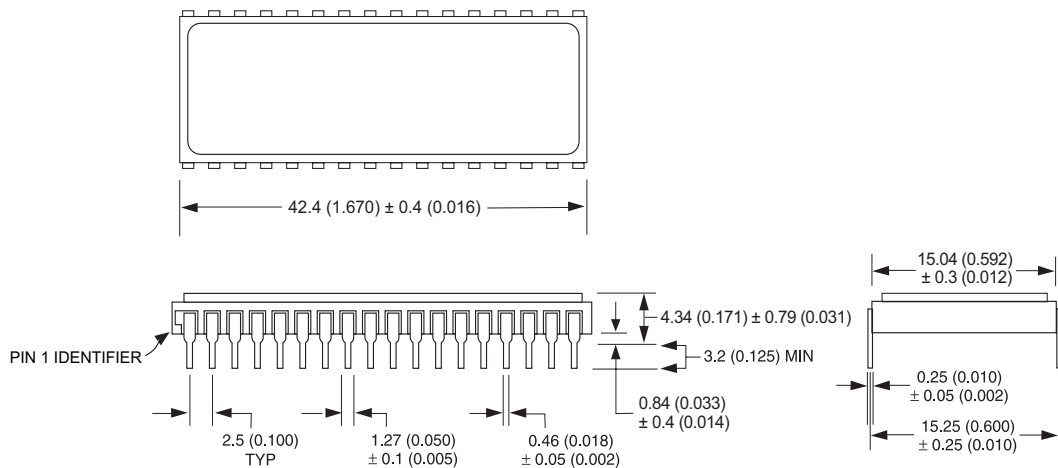


WRITE CYCLE – CS# CONTROLLED





PACKAGE 300: 32 PIN, CERAMIC DIP, SINGLE CAVITY SIDE BRAZED



ALL LINEAR DIMENSIONS ARE MILLIMETERS AND PARENTHETICALLY IN INCHES

ORDERING INFORMATION

W S 1M8 - XXX C X X

LEAD FINISH:

Blank = Gold plated leads

A = Solder dip leads

DEVICE GRADE:

M = Military Screened -55°C to +125°C

I = Industrial -40°C to +85°C

C = Commercial 0°C to +70°C

PACKAGE:

C = Ceramic 0.600" DIP (Package 300)

ACCESS TIME (ns)

ORGANIZATION, two banks of 512K x 8

SRAM

WHITE ELECTRONIC DESIGNS CORP.